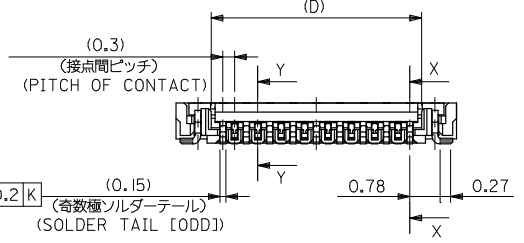
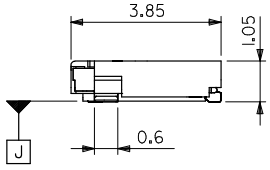
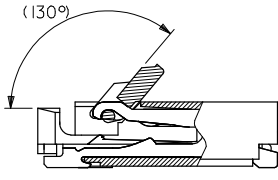
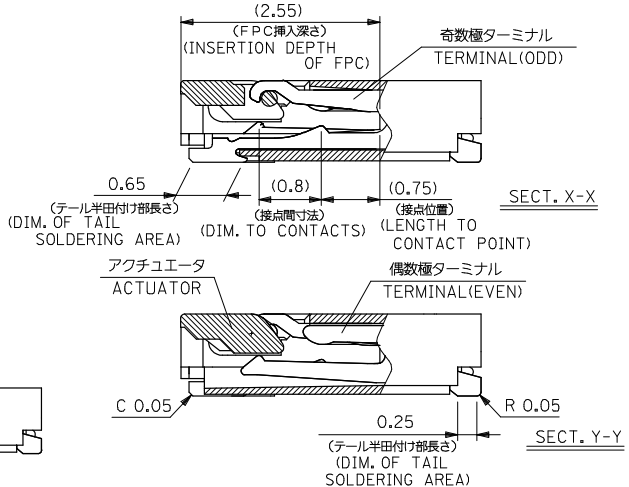
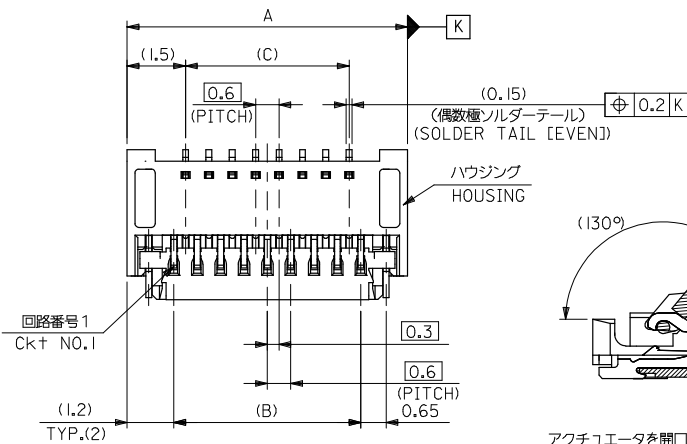


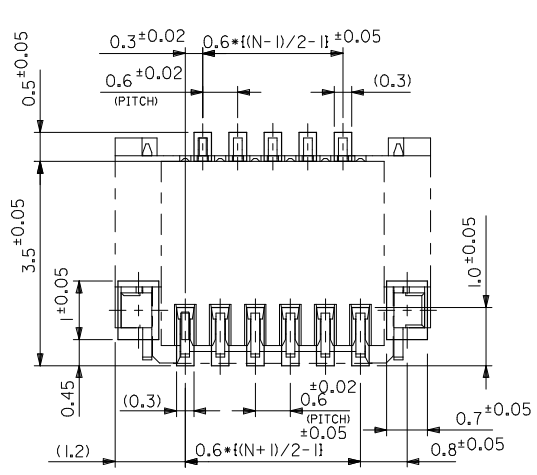
10 9 8 7 6 5 4 3 2 1



15.6	14.4	15.0	17.4	500797-5194	500797-5150	51
12.6	11.4	12.0	14.4	500797-4194	500797-4150	41
12.0	10.8	11.4	13.8	500797-3994	500797-3950	39
10.8	9.6	10.2	12.6	500797-3594	500797-3550	35
10.2	9.0	9.6	12.0	500797-3394	500797-3350	33
9.6	8.4	9.0	11.4	500797-3194	500797-3150	31
8.4	7.2	7.8	10.2	500797-2794	500797-2750	27
7.8	6.6	7.2	9.6	500797-2594	500797-2550	25
7.2	6.0	6.6	9.0	500797-2394	500797-2350	23
5.4	4.2	4.8	7.2	500797-1794	500797-1750	17
4.8	3.6	4.2	6.6	500797-1594	500797-1550	15
3.6	2.4	3.0	5.4	500797-1194	500797-1150	11
D	C	B	A	EMBOSSED TAPE	MATERIAL NO.	CKT.
				ORDER No. オート番号		

REVISED EC NO: J2008-4034 DRAWN BY: 2008/05/28 CHYKO:THAYUAMA APPR: NUKITA 2008/05/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY YMAEDA	DATE 2006/03/07	TITLE 0.3 FPC CONN E/O HSG ASSY (HGT=1.05MM) GOLD PLATING -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY MTANAKA	DATE 2006/03/07	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY NUKITA	DATE 2006/03/07	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-500797-005	SHEET NO. 1 OF 2
ANGULAR ±3°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

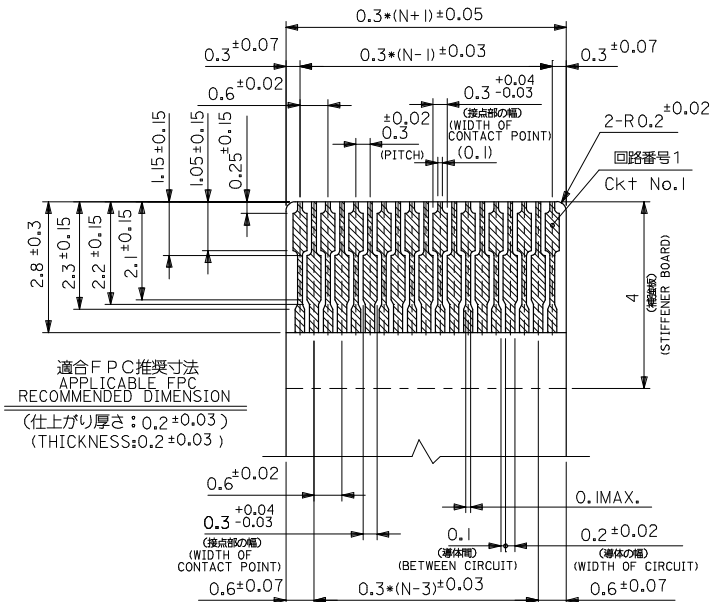
10 9 8 7 6 5 4 3 2 1



参考基板レイアウト図
(マウント面)
(MOUNTING SIDE)

注記 NOTES

1. 使用材料 MATERIAL
 ハウジング : 液晶ポリマー ガラス充填 UL94V-0
 HOUSING : LIQUID CRYSTAL POLYMER (GLASS FILLED) UL94V-0
 アクチュエータ : 46 ナイロン ガラス充填 UL94V-0
 ACTUATOR : 46 NYLON (GLASS FILLED) UL94V-0
 ターミナル : 銅合金 (t=0.15), ニッケル下地メッキ
 TERMINAL : COPPER ALLOY, GOLD OVER NICKEL PLATING.
 金具 : リン青銅 (t=0.15), ニッケル下地メッキ
 FITTING NAIL : PHOSPHOR-BRONZE, TIN OVER NICKEL PLATING.
 △ ソルダータール半田付け面のズレ量, 及び金具半田付け面のズレ量は, 基準面 □ に対し,
 上方向 0.1MAXIMUM, 下方向 0.15MAXIMUM とする。
 又, 相互のバラツキ量は 0.1MAXIMUM とする。
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM □
 UPPER DIRECTION : 0.1 MAXIMUM, LOWER DIRECTION : 0.15 MAXIMUM.
 OFFSET BETWEEN SOLDER TAILS AND FITTING NAILS : 0.1 MAXIMUM.



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

FPCについて:
 打抜き方向は導体側から補強板側を推奨いたします。
 導体側については軟銅箔35マイクロメートルまたは50マイクロメートルを
 推奨致します。
 補強フィルム材質はポリイミドを推奨します。
 接着剤は熱硬化接着剤を推奨します。

ABOUT FPC
 RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
 RECOMMENDED CONDUCTOR SPEC :
 THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER
 RECOMMENDED MATERIAL :
 STIFFENER FILM : POLYIMIDE
 BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO: J2008-4034 DRAWN BY: DRWNMBEL CHKD: THARYAMA APPR: NUKITA	DESCRIPTION 2008/05/28 2008/05/28 2008/05/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY YMAEDA	DATE 2006/03/06	TITLE 0.3 FPC CONN E/O HSG ASSY (HGT=1.05MM) GOLD PLATING -LEAD FREE-			
		10 OVER 30 UNDER	± 0.25	CHECKED BY MTANAKA	DATE 2006/03/06	MOLEX INCORPORATED			
		30 OVER	± 0.3	APPROVED BY NUKITA	DATE 2006/03/06				
ANGULAR ± 3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-500797-005	SHEET NO. 2 OF 2			

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

E

D

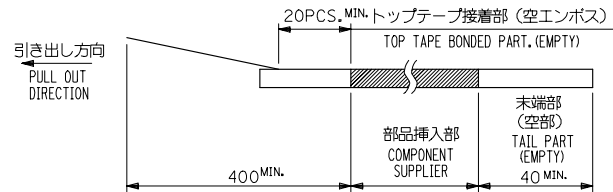
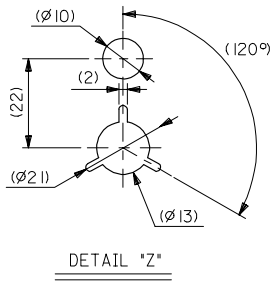
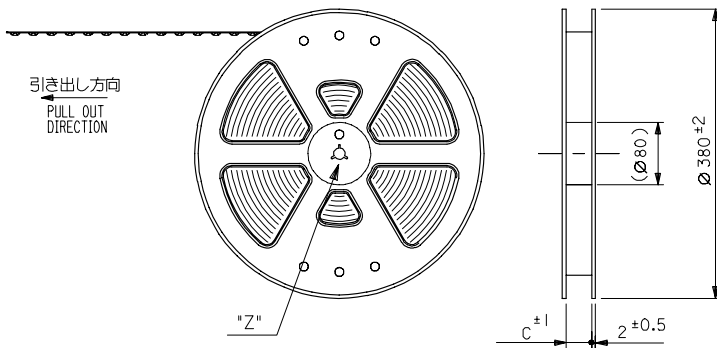
C

B

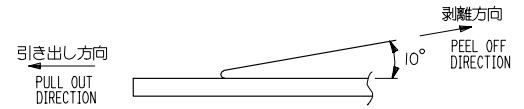
A

NOTES

- 製品詳細寸法については図面 SD-500797-005 を参照下さい。
RE DETAILED DIMENSION, SEE SD-500797-005
- 梱包数量：3000個/リール
NUMBER OF CONNECTORS : 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：0.1N ~ 1.3N(10.2gf ~ 132.6gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 0.7N(10.2gf ~ 71.4gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE) : ポリプロピレン (POLYPROPYLENE)
トップテープ (TOP TAPE) : PET , PE , PEF
リール (REEL) : ポリスチレン (PS) <リサイクル材含む>
POLYSTYREN (PS) <RECYCLE MATERIAL CONTAINED>
- C寸法は SHEET 2 ~ 4 を参照下さい。
SEE SHEET 2 ~ 4 (DIMENSION C).
- 欠品無きこと。
THERE SHALL BE NO MISSING PRODUCTS.

REVISED EC NO: J2008-003 DRAWN: HAYASHI 2007/07/02 CHKD: MORIKAWA 2007/07/02 APPR: MORIKAWA 2007/07/03	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	500797-x*94	MODEL NO.
	10 UNDER	±0.2	DRAWN BY YMAEDA	DATE 2006/03/07	TITLE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 OVER 30 UNDER	±0.25	CHECKED BY MTANAKA	DATE 2006/03/07	EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.05MM) GOLD PLATING -LEAD FREE- MOLEX INCORPORATED	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-500797-006
	30 OVER	±0.3	APPROVED BY NUKITA	DATE 2006/03/07			
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		EN-02JA(021)	

9

8

7

6

5

4

3

2

EN-02JA(021)

10 9 8 7 6 5 4 3 2 1

F F

E E

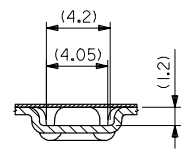
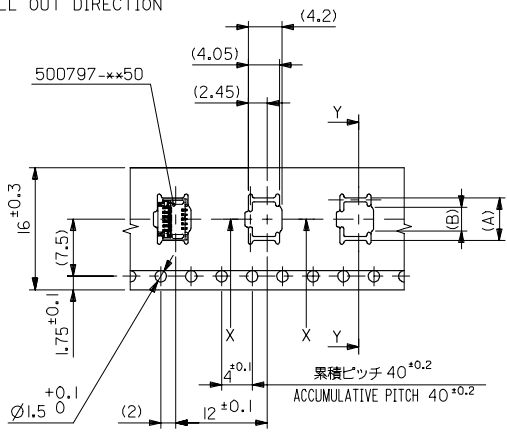
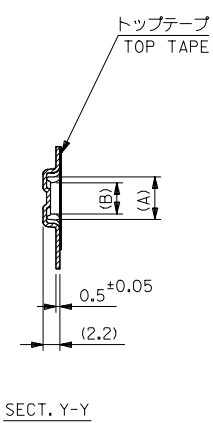
D D

C C

B B

A A

引き出し方向
PULL OUT DIRECTION



16mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

16	17.5	4.6	6.8	500797-1594	15
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	500797-1194	11
				製品番号 MATERIAL No.	種数 Ck ±
				500797-xx94	MODEL No.

REVISED EC NO: J2008-003 DRW: HAYASHI 2007/07/02 CHK: K. MORIKAWA 2007/07/02 APPR: MORIKAWA 2007/07/03 B REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY YMAEDA	DATE 2006/03/07	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.05MM) GOLD PLATING -LEAD FREE- MOLEX INCORPORATED		
	10 OVER 30 UNDER	± 0.25	CHECKED BY MTANAKA	DATE 2006/03/07			
	30 OVER	± 0.3	APPROVED BY NUKITA	DATE 2006/03/07			
	ANGULAR ± 3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-500797-006		2 OF 4	

10 9 8 7 6 5 4 3 2 1

F F

E E

D D

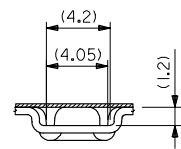
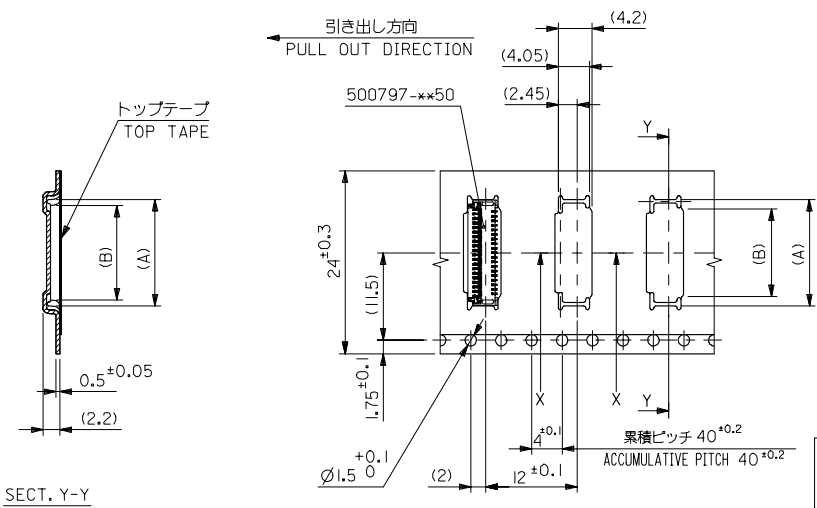
C C

B B

A A

9 8 7 6 5 4 3 2 1

EN-02JA(021)



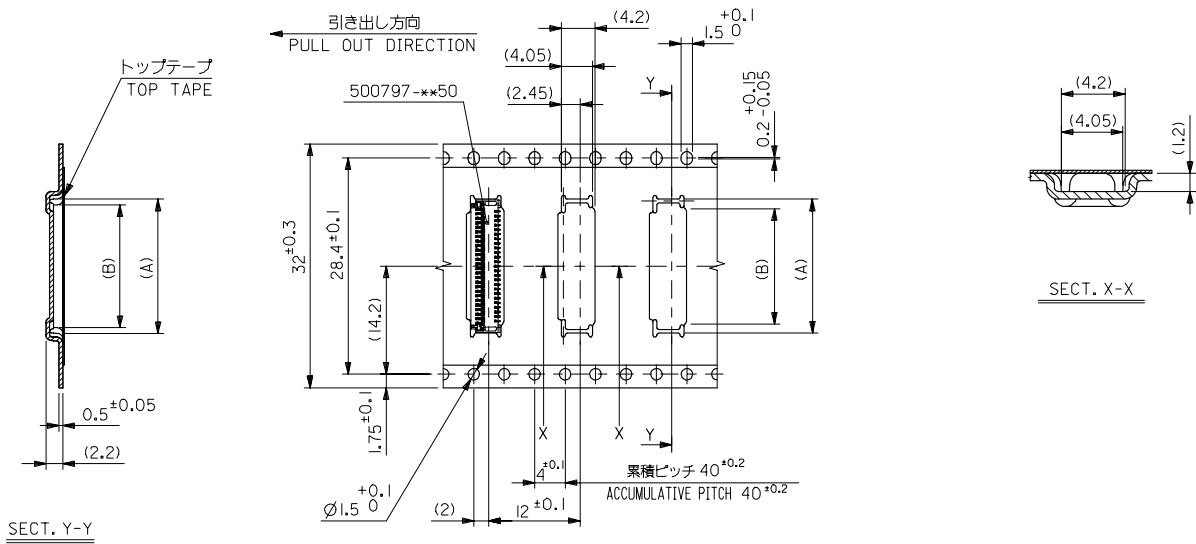
SECT. Y-Y

SECT. X-X

24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE

24	25.5	12.4	14.6	500797-4194	41
		11.8	14.0	500797-3994	39
		10.6	12.8	500797-3594	35
		10.0	12.2	500797-3394	33
		9.4	11.6	500797-3194	31
		8.2	10.4	500797-2794	27
		7.6	9.8	500797-2594	25
		7.0	9.2	500797-2394	23
5.2	7.4	500797-1794	17		
キャリアテープ幅 CARRIER TAPE WIDTH		C	(B)	(A)	製品番号 MATERIAL No.
				500797-xx94	極数 MODEL No. Ck†

REVISED EC NO. J2008-003 DRW: HAYASHI 2007/07/02 CHK: K. MORIKAWA 2007/07/02 APPR: K. MORIKAWA 2007/07/03	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY YMAEDA	DATE 2006/03/07	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.05MM) GOLD PLATING -LEAD FREE- MOLEX MOLEX INCORPORATED		
	10 OVER 30 UNDER	±0.25	CHECKED BY MTANAKA	DATE 2006/03/07			
	30 OVER	±0.3	APPROVED BY NUKITA	DATE 2006/03/07			
	ANGULAR	±3 °	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-500797-006	SHEET NO. 3 OF 4	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



32	33.5	15.4	17.6	500797-5194	51
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	製品番号 MATERIAL No.	種数 Ck±
				500797-**-**94	MODEL No.

REVISED EC NO. J2008-0003 DRW:MHAYASHI 2007/07/02 CHK:K.MORIKAWA 2007/07/02 APPR:MMORIKAWA 2007/07/03	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY YMAEDA	DATE 2006/03/07	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.05MM) GOLD PLATING -LEAD FREE- MOLEX INCORPORATED		
	10 OVER 30 UNDER	±0.25	CHECKED BY MTANAKA	DATE 2006/03/07			
	30 OVER	±0.3	APPROVED BY NUKITA	DATE 2006/03/07			
	ANGULAR	±3 °	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-500797-006	SHEET NO. 4 OF 4	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					